TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

# TD62107P,TD62107BP,TD62107F

#### 4CH HIGH-CURRENT DARLINGTON SINK DRIVER

The TD62107P / BP / F are high–voltage, high–current darlington drivers and enable inputs which can gate the outputs. All units feature integral clamp diodes for switching inductive loads. The TD62107P / BP / F have a wide supply voltage range and all

The TD62107P / BP / F have a wide supply voltage range and all input are compatible with TTL and 5–V CMOS.

Application include relay, hammer, lamp and stepping moter drivers.

Please observe the thermal condition for using.

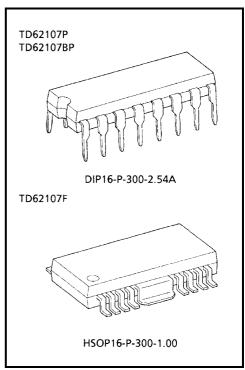
#### **FEATURES**

- Output current (single output) 750mA (MAX)
- High sustaining voltage output 80 V MIN. (TD62107BP)

45 V MIN. (TD62107P) 35 V MIN. (TD62107F)

- Output clamp diodes
- Enable inputs E1, E2
- Wide supply voltage range  $VCC = 4.75 \sim 17 \text{ V}$
- Input compatible with TTL and 5-V CMOS
- GND terminal = heat sink

Package type-P, BP : DIP-16pinPackage type-F : HSOP-16pin

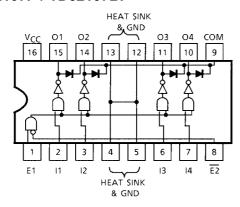


Weight

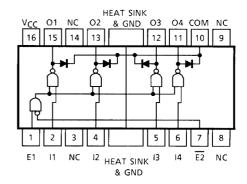
DIP16-P-300-2.54A : 1.11 g (Typ.) HSOP16-P-300-1.00 : 0.50 g (Typ.)

#### **PIN CONNECTION (TOP VIEW)**

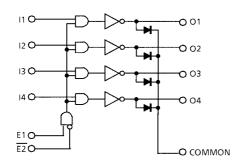
#### TD62107P / TD62107BP



#### **TD62107F**



# SCHEMATICS (EACH DRIVER)

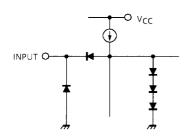


#### **TRUTH TABLE**

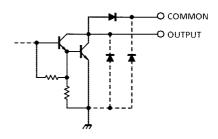
E1	E2	I1 ~ I4 O1~O4			
L	L	L or H	Disable OFF		
L	Н	L or H	Disable OFF		
Н	L	L or H	Enable In		
Н	Н	L or H	Disable OFF		

In = I1 ~ I4

## **INPUT EQUIVALENT CIRCUIT**



## **OUTPUT EQUIVALENT CIRCUIT**



Note: The input and output parasitic diodes cannot be used as clamp diodes.

# MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT		
Supply Voltage	V <sub>CC</sub>	-0.5~17	V		
	Р		-0.5~45		
Output Sustaining Voltage	BP	V <sub>CE</sub> (SUS)	-0.5~80	V	
	F		-0.5~35		
Output Current	I <sub>OUT</sub> 750			mA	
Input Voltage		V <sub>IN</sub>	-0.5~V <sub>CC</sub> + 0.5	V	
	Р		45	V	
Clamp Diode Reverse Voltage	BP	$V_{R}$	80		
	F		35		
Clamp Diode Forword Current	P, F	I <sub>F</sub>	500	- mA	
Clamp blode i diword Current	BP	'F	750		
Power Dissipation	P, BP	P <sub>D</sub>	2.7 (Note 1)	W	
Fower Dissipation	F	L.D	1.4 (Note 2)		
Operating Temperature		T <sub>opr</sub>	-40~85	°C	
Storage Temperature		T <sub>stg</sub>	-55~150	°C	

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Note 1: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 50%) Note 2: On Glass Epoxy PCB (60 × 30 × 1.6 mm Cu 30%)

# RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)

CHARACTERISTIC		SYMBOL	CONDITION		MIN	TYP.	MAX	UNIT
Supply Voltage		V <sub>CC</sub>			4.75	_	15	V
Output Sustaining Voltage	Р	V <sub>CE</sub> (SUS)			0	_	45	
	BP				0	_	80	V
	F				0	_	35	
0.4	P, F		T <sub>pw</sub> = 25ms, Duty = 75%	y = 75%, 1 Circuit		_	500	mA
	BP	Гоит	T <sub>pw</sub> = 25ms, Duty = 10%	pw = 25ms, Duty = 10%, 4 Circuits		_	750	
Output Current	P, BP		T <sub>pw</sub> = 25ms, 4 Circuits	Duty = 30%	0	_	400	mA
	F			Duty = 40%	_	_	300	
Input Voltage	nput Voltage				0	_	V <sub>CC</sub>	V
	Р	V <sub>R</sub>			_	_	45	
Clamp Diode ReverseVoltage	BP				_	_	80	V
	F				_	_	35	
Clamp Diode Forward Current	P, F	lF			_	_	500	mA
	BP				_	_	750	IIIA
Power Dissipation	B, BP	P <sub>D</sub>			_	_	1.0	W
	F		Ta = 85°C	(Note)	_	_	0.7	VV

Note: On Glass Epoxy PCB (60 × 30 × 1.6 mm Cu 30%)

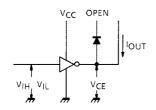
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# **ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

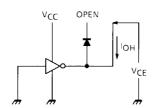
CHARACTERISTIC		SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT	
Voltage	"H" Level		V <sub>IH</sub>	1		2.0	_	V <sub>CC</sub>	- V
	"L" Level	"L" Level				_	_	8.0	
Output Current	"H" Level	Р		2	V <sub>CE</sub> = 45 V, Ta = 75°C	_	_	100	μA
		BP	I <sub>OH</sub>		V <sub>CE</sub> = 80 V, Ta = 85°C	_	_	100	
		F			V <sub>CE</sub> = 35 V, Ta = 85°C	_	_	100	
Output	"L" Level	P, F		3	I <sub>OUT</sub> = 50 mA	_	_	1.3	- V
Voltage	L Level	BP	V <sub>OL</sub>	3	I <sub>OUT</sub> = 750 mA	_	_	1.6	
Input	"H" Level		I <sub>IH</sub>	4	V <sub>IN</sub> = 13 V	_	_	100	μΑ
Current	"L" Level	I <sub>IL</sub>		5	$V_{IN} = 0.4 \text{ V}$	_	_	-0.3	mA
		Р			V <sub>R</sub> = 45 V	_	_	100	μΑ
Clamp Diode Reverse Current	de Reverse	BP	I <sub>R</sub>	6	V <sub>R</sub> = 80 V	_	_	100	
Guitent		F			V <sub>R</sub> = 35 V	_	_	100	
Clamp Diode Forward		P, F	V <sub>F</sub>	7	I <sub>F</sub> = 500 mA	_	_	2.0	V
Voltage	BP	I <sub>F</sub> = 750 mA			_	_	2.0		
Supply	Output "H"	- ICC	Іссн	4	V <sub>CC</sub> = 13 V, V <sub>IN</sub> = 0 V, OUTPUT OPEN	_	_	13	mA
Current	Output "L"		I <sub>CCL</sub>	5	V <sub>CC</sub> = 13 V, V <sub>IN</sub> = 5 V, OUTPUT OPEN	_	_	17	IIIA
	Р			8	V <sub>CC</sub> = 5 V, R <sub>L</sub> = 90 Ω C <sub>L</sub> = 15 pF, V <sub>OUT</sub> = 45 V	_	5	_	
Turn-On Delay		BP	t <sub>ON</sub>		V <sub>CC</sub> = 5 V, V <sub>OUT</sub> = 80 V R <sub>L</sub> = 160 Ω	_	0.4	_	μs
		F			$V_{CC}$ = 5 V, $R_L$ = 70 $\Omega$ $C_L$ = 15 pF, $V_{OUT}$ = 35 V	_	5	_	
Turn-Off Delay BP			$V_{CC}$ = 5 V, $R_L$ = 90 $\Omega$ $C_L$ = 15 pF, $V_{OUT}$ = 45 V	-	5	_			
		BP	toff	8	V <sub>CC</sub> = 5 V, V <sub>OUT</sub> = 80 V R <sub>L</sub> = 160 Ω	_	1.7	_	μs
		F			V <sub>CC</sub> = 5 V, R <sub>L</sub> = 70 Ω C <sub>L</sub> = 15 pF, V <sub>OUT</sub> = 35 V	_	5	_	

#### **TEST CIRCUIT**

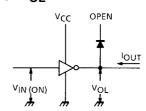
#### 1. VIH, VIL



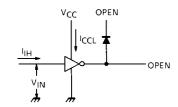
#### 2. I<sub>OH</sub>



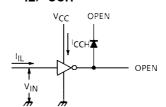
#### 3. Vol



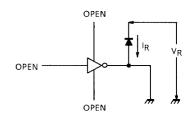
#### 4. I<sub>IH</sub>, I<sub>CCL</sub>



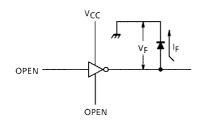
## 5. I<sub>IL</sub>, I<sub>CCH</sub>



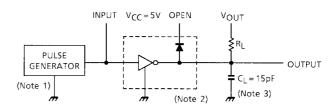
## 6. I<sub>R</sub>



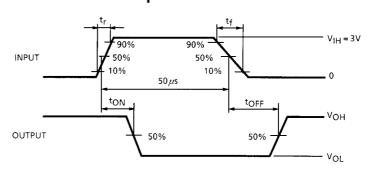
#### 7. V<sub>F</sub>



## 8. ton, toff



#### Input condition



Note 1: Pulse Width 50  $\mu s$ , Duty Cycle 10%

Output Impedance 50  $\Omega$ ,  $t_f \le 5$ ns,  $t_f \le 10$  ns

Note 2:  $V_{IH} = 3 V$ ,  $E1 = V_{IH}$ ,  $\overline{E2} = GND$ ,

 $V_{CC} = 5 V$ 

Note 3: C<sub>L</sub> includes probe and jig capacitance

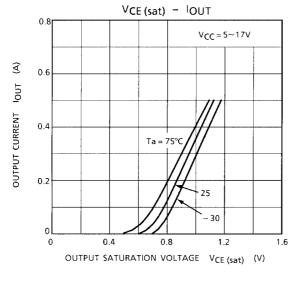
#### PRECAUTIONS for USING

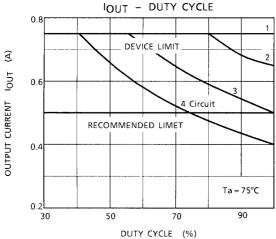
This IC does not include built-in protection circuits for excess current or overvoltage.

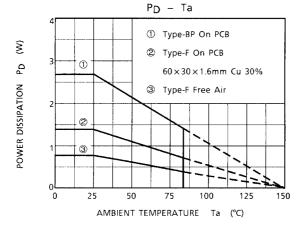
If this IC is subjected to excess current or overvoltage, it may be destroyed.

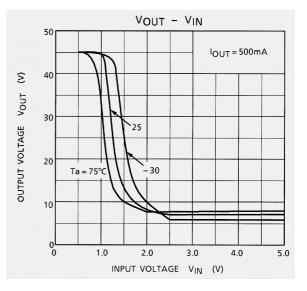
Hence, the utmost care must be taken when systems which incorporate this IC are designed.

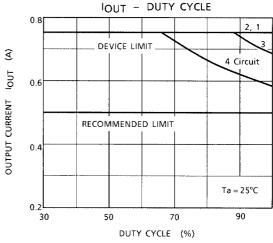
Utmost care is necessary in the design of the output line, V<sub>CC</sub>, COMMON and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

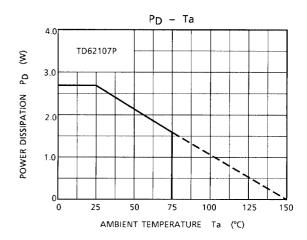






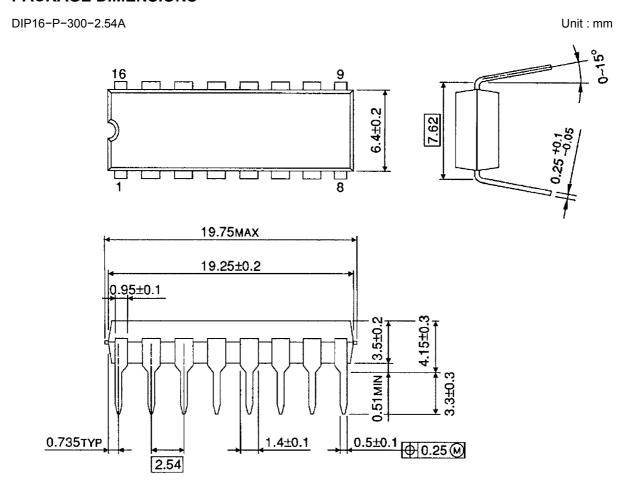






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## **PACKAGE DIMENSIONS**

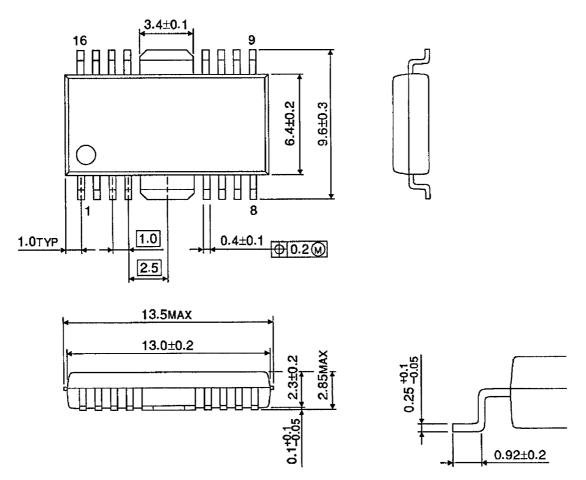


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Weight: 1.11 g (Typ.)

## **PACKAGE DIMENSIONS**

HSOP16-P-300-1.00 Unit: mm



Weight: 0.50 g (Typ.)

#### **RESTRICTIONS ON PRODUCT USE**

000707EBA

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